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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	21
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16К х 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc802t-i-mm

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 AND dsPIC33FJ128MCX02/X04 PRODUCT FAMILIES

The device names, pin counts, memory sizes, and peripheral availability of each device are listed in Table 1. The pages that follow show their pinout diagrams.

TABLE 1:dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 AND dsPIC33FJ128MCX02/X04CONTROLLER FAMILIES

						l	Remap	pable F	eriphe	ral			1).			
Device	Pins	Program Flash Memory (Kbyte)	RAM (Kbyte) ⁽¹⁾	Remappable Pins	16-bit Timer ⁽²⁾	Input Capture	Output Compare Standard PWM	Motor Control PWM (Channels) ⁽³⁾	Quadrature Encoder Interface	UART	IdS	ECANTM	External Interrupts ⁽⁴⁾	RTCC	I²C™	CRC Generator	10-bit/12-bit ADC (Channels)	6-pin 16-bit DAC	Analog Comparator (2 Channels/Voltage Regulat	8-bit Parallel Master Port (Address Lines)	I/O Pins	Packages
dsPIC33FJ128MC804	44	128	16	26	5	4	4	6, 2	2	2	2	1	3	1	1	1	9	1	1/1	11	35	QFN TQFP
dsPIC33FJ128MC802	28	128	16	16	5	4	4	6, 2	2	2	2	1	3	1	1	1	6	0	1/0	2	21	SPDIP SOIC QFN-S
dsPIC33FJ128MC204	44	128	8	26	5	4	4	6, 2	2	2	2	0	3	1	1	1	9	0	1/1	11	35	QFN TQFP
dsPIC33FJ128MC202	28	128	8	16	5	4	4	6, 2	2	2	2	0	3	1	1	1	6	0	1/0	2	21	SPDIP SOIC QFN-S
dsPIC33FJ64MC804	44	64	16	26	5	4	4	6, 2	2	2	2	1	3	1	1	1	9	1	1/1	11	35	QFN TQFP
dsPIC33FJ64MC802	28	64	16	16	5	4	4	6, 2	2	2	2	1	3	1	1	1	6	0	1/0	2	21	SPDIP SOIC QFN-S
dsPIC33FJ64MC204	44	64	8	26	5	4	4	6, 2	2	2	2	0	3	1	1	1	9	0	1/1	11	35	QFN TQFP
dsPIC33FJ64MC202	28	64	8	16	5	4	4	6, 2	2	2	2	0	3	1	1	1	6	0	1/0	2	21	SPDIP SOIC QFN-S
dsPIC33FJ32MC304	44	32	4	26	5	4	4	6, 2	2	2	2	0	3	1	1	1	9	0	1/1	11	35	QFN TQFP
dsPIC33FJ32MC302	28	32	4	16	5	4	4	6, 2	2	2	2	0	3	1	1	1	6	0	1/0	2	21	SPDIP SOIC QFN-S

Note 1: RAM size is inclusive of 2 Kbytes of DMA RAM for all devices except dsPIC33FJ32MC302/304, which include 1 Kbyte of DMA RAM.

2: Only four out of five timers are remappable.

3: Only PWM fault pins are remappable.

4: Only two out of three interrupts are remappable.

Part Number	Vendor	Freq.	Load Cap.	Package Case	Frequency Tolerance	Mounting Type	Operating Temperature
FCR4.0M5T	TDK Corp.	4 MHz	N/A	Radial	±0.5%	TH	-40°C to +85°C
FCR8.0M5	TDK Corp.	8 MHz	N/A	Radial	±0.5%	TH	-40°C to +85°C
HWZT-10.00MD	TDK Corp.	10 MHz	N/A	Radial	±0.5%	TH	-40°C to +85°C
HWZT-20.00MD	TDK Corp.	20 MHz	N/A	Radial	±0.5%	TH	-40°C to +85°C

|--|

Legend: TH = Through Hole

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to less than or equal to 8 MHz for start-up with PLL enabled to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the analog-to-digital input pins (ANx) as "digital" pins, by setting all bits in the AD1PCFGL register.

The bits in this register that correspond to the analog-to-digital pins that are initialized by MPLAB ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain analog-to-digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

When MPLAB ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all analog-to-digital pins being recognized as analog input pins, resulting in the port value being read as a logic '0', which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor between Vss and the unused pin.

3.8.1 MULTIPLIER

The 17-bit x 17-bit multiplier is capable of signed or unsigned operation and can multiplex its output using a scaler to support either 1.31 fractional (Q31) or 32-bit integer results. Unsigned operands are zero-extended into the 17th bit of the multiplier input value. Signed operands are sign-extended into the 17th bit of the multiplier input value. Signed to 40 bits. Integer data is inherently represented as a signed two's complement value, where the Most Significant bit (MSb) is defined as a sign bit. The range of an N-bit two's complement integer is -2^{N-1} to $2^{N-1} - 1$.

- For a 16-bit integer, the data range is -32768 (0x8000) to 32767 (0x7FFF) including 0
- For a 32-bit integer, the data range is
 -2,147,483,648 (0x8000 0000) to 2,147,483,647 (0x7FFF FFFF)

When the multiplier is configured for fractional multiplication, the data is represented as a two's complement fraction, where the MSb is defined as a sign bit and the radix point is implied to lie just after the sign bit (QX format). The range of an N-bit two's complement fraction with this implied radix point is -1.0 to $(1 - 2^{1-N})$. For a 16-bit fraction, the Q15 data range is -1.0 (0x8000) to 0.999969482 (0x7FFF) including 0 and has a precision of 3.01518x10⁻⁵. In Fractional mode, the 16 x 16 multiply operation generates a 1.31 product that has a precision of 4.65661 x 10⁻¹⁰.

The same multiplier is used to support the MCU multiply instructions, which include integer 16-bit signed, unsigned and mixed sign multiply operations.

The MUL instruction can be directed to use byte or word-sized operands. Byte operands direct a 16-bit result, and word operands direct a 32-bit result to the specified registers in the W array.

3.8.2 DATA ACCUMULATORS AND ADDER/SUBTRACTER

The data accumulator consists of a 40-bit adder/ subtracter with automatic sign extension logic. It can select one of two accumulators (A or B) as its pre-accumulation source and post-accumulation destination. For the ADD and LAC instructions, the data to be accumulated or loaded can be optionally scaled using the barrel shifter prior to accumulation.

3.8.2.1 Adder/Subtracter, Overflow and Saturation

The adder/subtracter is a 40-bit adder with an optional zero input into one side, and either true or complement data into the other input.

- In the case of addition, the Carry/Borrow input is active-high and the other input is true data (not complemented)
- In the case of subtraction, the Carry/Borrow input is active-low and the other input is complemented

The adder/subtracter generates Overflow Status bits, SA/SB and OA/OB, which are latched and reflected in the STATUS register:

- Overflow from bit 39: this is a catastrophic overflow in which the sign of the accumulator is destroyed
- Overflow into guard bits 32 through 39: this is a recoverable overflow. This bit is set whenever all the guard bits are not identical to each other.

The adder has an additional saturation block that controls accumulator data saturation, if selected. It uses the result of the adder, the Overflow Status bits described previously and the SAT<A:B> (CORCON<7:6>) and ACCSAT (CORCON<4>) mode control bits to determine when and to what value to saturate.

Six STATUS register bits support saturation and overflow:

- · OA: ACCA overflowed into guard bits
- · OB: ACCB overflowed into guard bits

or

• SA: ACCA saturated (bit 31 overflow and saturation)

ACCA overflowed into guard bits and saturated (bit 39 overflow and saturation)

 SB: ACCB saturated (bit 31 overflow and saturation) or

ACCB overflowed into guard bits and saturated (bit 39 overflow and saturation)

- OAB: Logical OR of OA and OB
- · SAB: Logical OR of SA and SB

The OA and OB bits are modified each time data passes through the adder/subtracter. When set, they indicate that the most recent operation has overflowed into the accumulator guard bits (bits 32 through 39). The OA and OB bits can also optionally generate an arithmetic warning trap when set and the corresponding Overflow Trap Flag Enable bits (OVATE, OVBTE) in the INTCON1 register are set (refer to **Section 7.0 "Interrupt Controller"**). This allows the user application to take immediate action, for example, to correct system gain.

The SA and SB bits are modified each time data passes through the adder/subtracter, but can only be cleared by the user application. When set, they indicate that the accumulator has overflowed its maximum range (bit 31 for 32-bit saturation or bit 39 for 40-bit saturation) and is saturated (if saturation is enabled). When saturation is not enabled, SA and SB default to bit 39 overflow and thus indicate that a catastrophic overflow has occurred. If the COVTE bit in the INTCON1 register is set, the SA and SB bits generate an arithmetic warning trap when saturation is disabled. The Overflow and Saturation Status bits can optionally be viewed in the STATUS Register (SR) as the logical OR of OA and OB (in bit OAB) and the logical OR of SA and SB (in bit SAB). Programmers can check one bit in the STATUS register to determine if either accumulator has overflowed, or one bit to determine if either accumulator has saturated. This is useful for complex number arithmetic, which typically uses both accumulators.

The device supports three Saturation and Overflow modes:

- Bit 39 Overflow and Saturation:
- When bit 39 overflow and saturation occurs, the saturation logic loads the maximally positive 9.31 (0x7FFFFFFFFF) or maximally negative 9.31 value (0x800000000) into the target accumulator. The SA or SB bit is set and remains set until cleared by the user application. This condition is referred to as super saturation and provides protection against erroneous data or unexpected algorithm problems (such as gain calculations).
- Bit 31 Overflow and Saturation: When bit 31 overflow and saturation occurs, the saturation logic then loads the maximally positive 1.31 value (0x007FFFFFF) or maximally negative 1.31 value (0x0080000000) into the target accumulator. The SA or SB bit is set and remains set until cleared by the user application. When this Saturation mode is in effect, the guard bits are not used, so the OA, OB or OAB bits are never set.
- Bit 39 Catastrophic Overflow: The bit 39 Overflow Status bit from the adder is used to set the SA or SB bit, which remains set until cleared by the user application. No saturation operation is performed, and the accumulator is allowed to overflow, destroying its sign. If the COVTE bit in the INTCON1 register is set, a catastrophic overflow can initiate a trap exception.

3.8.3 ACCUMULATOR WRITE BACK

The MAC class of instructions (with the exception of MPY, MPY.N, ED and EDAC) can optionally write a rounded version of the high word (bits 31 through 16) of the accumulator that is not targeted by the instruction into data space memory. The write is performed across the X bus into combined X and Y address space. The following addressing modes are supported:

- W13, Register Direct: The rounded contents of the non-target accumulator are written into W13 as a 1.15 fraction.
- [W13] + = 2, Register Indirect with Post-Increment: The rounded contents of the non-target accumulator are written into the address pointed to by W13 as a 1.15 fraction. W13 is then incremented by 2 (for a word write).

3.8.3.1 Round Logic

The round logic is a combinational block that performs a conventional (biased) or convergent (unbiased) round function during an accumulator write (store). The Round mode is determined by the state of the RND bit in the CORCON register. It generates a 16-bit, 1.15 data value that is passed to the data space write saturation logic. If rounding is not indicated by the instruction, a truncated 1.15 data value is stored, and the least significant word is simply discarded.

Conventional rounding zero-extends bit 15 of the accumulator and adds it to the ACCxH word (bits 16 through 31 of the accumulator).

- If the ACCxL word (bits 0 through 15 of the accumulator) is between 0x8000 and 0xFFFF (0x8000 included), ACCxH is incremented.
- If ACCxL is between 0x0000 and 0x7FFF, ACCxH is left unchanged.

A consequence of this algorithm is that over a succession of random rounding operations, the value tends to be biased slightly positive.

Convergent (or unbiased) rounding operates in the same manner as conventional rounding, except when ACCxL equals 0x8000. In this case, the Least Significant bit (bit 16 of the accumulator) of ACCxH is examined:

- If it is '1', ACCxH is incremented.
- If it is '0', ACCxH is not modified.

Assuming that bit 16 is effectively random in nature, this scheme removes any rounding bias that may accumulate.

The SAC and SAC.R instructions store either a truncated (SAC), or rounded (SAC.R) version of the contents of the target accumulator to data memory via the X bus, subject to data saturation (see **Section 3.8.3.2 "Data Space Write Saturation**"). For the MAC class of instructions, the accumulator write-back operation functions in the same manner, addressing combined MCU (X and Y) data space though the X bus. For this class of instructions, the data is always subject to rounding.

4.0 MEMORY ORGANIZATION

Note:	This data sheet summarizes the features
	of the dsPIC33FJ32MC302/304,
	dsPIC33FJ64MCX02/X04 and
	dsPIC33FJ128MCX02/X04 family of
	devices. It is not intended to be a
	comprehensive reference source. To
	complement the information in this data
	sheet, refer to Section 4. "Program
	Memory" (DS70203) of the "dsPIC33F/
	PIC24H Family Reference Manual", which
	is available from the Microchip web site
	(www.microchip.com).

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 and dsPIC33FJ128MCX02/X04 architecture features separate program and data memory spaces and buses. This architecture also allows the direct access to program memory from the data space during code execution.

4.1 Program Address Space

The program address memory space of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in Section 4.8 "Interfacing Program and Data Memory Spaces".

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory map for the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 devices is shown in Figure 4-1.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 AND dsPIC33FJ128MCX02/X04 DEVICES

	dsPIC33FJ32MC302/304	dsPIC33FJ64MCX02/X04	dsPIC33FJ128MCX02/X04	
▲	GOTO Instruction	GOTO Instruction	GOTO Instruction 0x000000 Reset Address 0x000002	
	Interrupt Vector Table	Interrupt Vector Table	Interrupt Vector Table	
	Reserved	Reserved	0x0000FE	
		Alternate Vector Table	Alternate Vector Table 0x000104	
			0x0001FE	
Space	User Program Flash Memory (11264 instructions)	User Program Flash Memory	0x0057FE	
Memory 3		(22016 Instructions)	User Program Flash Memory (44032 instructions)	
User	Unimplemented			
	(Read '0's)	Unimplemented	0.046755	
	((Read '0's)	0x0157FE 0x015800	
		(Redu 03)		
			Unimplemented	
			(Read '0's)	
•			0x7FFFE	
Î	Reserved	Reserved	0x800000 Reserved	
ry Space	Device Configuration	Device Configuration	Device Configuration OxF7FFE OxF80000 Registers OxF80017	
ation Memo	Reserved	Reserved	Reserved	
nfigui			0xFEFFFE	
ပိ	DEVID (2)	DEVID (2)	DEVID (2) 0xFF0000 0xFF0002	
<u> </u>	Reserved	Reserved	Reserved	
Note	: Memory areas are not show	vn to scale.		





						• .												
File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	0680	_	_	_			INT1R<4:0>			_	_	_	_	_	_			1F00
RPINR1	0682	_	_	_	_	_	_	_	_	_	_	_			INT2R<4:0	>		001F
RPINR3	0686	_	_	_			T3CKR<4:0>			_	_	_			T2CKR<4:0	>		1F1F
RPINR4	0688	_	_	_			T5CKR<4:0>			_	_	_			T4CKR<4:0	>		1F1F
RPINR7	068E	_	_	_			IC2R<4:0>			_	_	_			IC1R<4:0>	•		1F1F
RPINR10	0694	_	_	_			IC8R<4:0>			_	_	_			IC7R<4:0>	•		1F1F
RPINR11	0696	_	_	_	_	_	_	_		_	_	_			OCFAR<4:)>		001F
RPINR12	0698	_	_	_	_	_	_	_	_	_	_	_	FLTA1R<4:0>			001F		
RPINR13	069A	_	_	_	_	_	_	_	_	_	_	_	FLTA2R<4:0>			001F		
RPINR14	069C	_	_	_			QEB1R<4:0>	•		_	_	_			QEA1R<4:0)>		1F1F
RPINR15	069E	_	_	_	_	_	_	_	_	_	_	_			INDX1R<4:)>		001F
RPINR16	06A0	_	_	_			QEB2R<4:0>	•		_	_	_			QEA2R<4:0)>		1F1F
RPINR17	06A2	_	_	_	_	_	_	_	_	_	_	_			INDX2R<4:)>		001F
RPINR18	06A4	_	_	_			U1CTSR<4:0	>		_	_	_			U1RXR<4:0)>		1F1F
RPINR19	06A6	_	_	_			U2CTSR<4:0	>		_	_	_			U2RXR<4:0)>		1F1F
RPINR20	06A8	_	_	_			SCK1R<4:0>			_	_	_			SDI1R<4:0	>		1F1F
RPINR21	06AA	_	_	_	_	_	_	_	_	_	_	_			SS1R<4:0	>		001F
RPINR22	06AC	_	_	_			SCK2R<4:0>	,		_	_	_			SDI2R<4:0	>		1F1F
RPINR23	06AE	_	_	_	_	_	_	_	_	_	_	_			SS2R<4:0	>		001F
RPINR26 ⁽¹⁾	06B4	_	_	_	_	_	_	_		_	_	_			C1RXR<4:0)>		001F

TABLE 4-24: PERIPHERAL PIN SELECT INPUT REGISTER MAP

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is present in dsPIC33FJ128MC802/804 and dsPIC33FJ64MC802/804 devices only.

_____ IC3

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10.0 POWER-SAVING FEATURES

- Note 1: This data sheet summarizes the features of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of devices. It is not intended to be a comprehensive reference source. То complement the information in this data sheet, refer to Section 9. Watchdog Timer and Power-Saving Modes" (DS70196) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 and dsPIC33FJ128MCX02/X04 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power.

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 and dsPIC33FJ128MCX02/X04 devices can manage power consumption in four ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- · Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 and dsPIC33FJ128MCX02/X04 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in detail in Section 9.0 "Oscillator Configuration".

10.2 Instruction-Based Power-Saving Modes

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/ X04 and dsPIC33FJ128MCX02/X04 devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to wake up.

10.2.1 SLEEP MODE

The following occur in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of the these events:

- · Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

PWRSAV #SLEEP_MODE ; Put the device into Sleep mode PWRSAV #IDLE MODE ; Put the device into Idle mode

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1 (CONTINUED)

- bit 2 Unimplemented: Read as '0'
- bit 1 C1MD: ECAN1 Module Disable bit
 - 1 = ECAN1 module is disabled
 - 0 = ECAN1 module is enabled
- bit 0 AD1MD: ADC1 Module Disable bit
 - 1 = ADC1 module is disabled 0 = ADC1 module is enabled

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
		_			SCK1R<4:0>	•	
bit 15							bit 8
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
_		_			SDI1R<4:0>		
bit 7							bit (
Legend:							
R = Readab	ole bit	W = Writable	bit	U = Unimpler	mented bit, rea	d as '0'	
-n = Value a	at POR	'1' = Bit is set	t	'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 12-8	SCK1R<4:0> 11111 = Inpu 11001 = Inpu	: Assign SPI1 ut tied to Vss ut tied to RP25	Clock Input (S	CK1) to the cc	prresponding R	Pn pin	
	00001 = Inpu 00000 = Inpu	ut tied to RP1 ut tied to RP0					
bit 7-5	Unimplemen	ited: Read as	0'				
bit 4-0	SDI1R<4:0>: 11111 = Inpu	Assign SPI1 [Data Input (SD	11) to the corre	esponding RPn	pin	

40 ... DIN SELECT INDUT DECISTED 20

00001 = Input tied to RP1 00000 = Input tied to RP0

15.0 OUTPUT COMPARE

- This data sheet summarizes the features Note 1: of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 of family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 13. "Output Compare" (DS70209) of the "dsPIC33F/ PIC24H Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Output Compare module can select either Timer2 or Timer3 for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the compare register value. The Output Compare module generates either a single output pulse or a sequence of output pulses, by changing the state of the output pin on the compare match events. The Output Compare module can also generate interrupts on compare match events.

The Output Compare module has multiple operating modes:

- Active-Low One-Shot mode
- Active-High One-Shot mode
- Toggle mode
- · Delayed One-Shot mode
- · Continuous Pulse mode
- PWM mode without fault protection
- · PWM mode with fault protection

FIGURE 15-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0				
FRMEN	SPIFSD	FRMPOL	—	—	—	—	—				
bit 15							bit 8				
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0				
—	—	—	_	—	—	FRMDLY	—				
bit 7							bit 0				
Legend:											
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'											
-n = Value at F	-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown										
bit 15	FRMEN: Fran	ned SPIx Supp	ort bit								
	1 = Framed SPIx support enabled (\overline{SSx} pin used as frame sync pulse input/output)										
0 = Framed SPIx support disabled											
bit 14 SPIFSD: Frame Sync Pulse Direction Control bit											
	1 = Frame sync pulse input (slave)										
	0 = Frame sy	nc pulse output	t (master)								
bit 13	FRMPOL: Fra	ame Sync Puls	e Polarity bit								

REGISTER 18-3: SPIxCON2: SPIx CONTROL REGISTER 2

1 = Frame sync pulse is active-high0 = Frame sync pulse is active-low

FRMDLY: Frame Sync Pulse Edge Select bit

1 = Frame sync pulse coincides with first bit clock0 = Frame sync pulse precedes first bit clock

Unimplemented: This bit must not be set to '1' by the user application

Unimplemented: Read as '0'

bit 12-2

bit 1

bit 0

FIGURE 22-3: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



REGISTER 25-8: ALRMVAL (WHEN ALRMPTR<1:0> = 10): ALARM MONTH AND DAY VALUE REGISTER⁽¹⁾

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0		MTHON	IE<3:0>	
bit 15							bit 8
U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x

0-0	0-0	R/W-X	R/W-X	R/W-X	R/W-X	R/W-X	R/W-X
—	—	DAYTE	N<1:0>		DAYON	IE<3:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13	Unimplemented: Read as '0'
bit 12	MTHTEN0: Binary Coded Decimal Value of Month's Tens Digit; contains a value of 0 or 1
bit 11-8	MTHONE<3:0>: Binary Coded Decimal Value of Month's Ones Digit; contains a value from 0 to 9
bit 7-6	Unimplemented: Read as '0'
bit 5-4	DAYTEN<1:0>: Binary Coded Decimal Value of Day's Tens Digit; contains a value from 0 to 3
bit 3-0	DAYONE<3:0>: Binary Coded Decimal Value of Day's Ones Digit; contains a value from 0 to 9

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 25-9: ALRMVAL (WHEN ALRMPTR<1:0> = 01): ALARM WEEKDAY AND HOURS VALUE REGISTER⁽¹⁾

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN<1:0>			HRON	E<3:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 Unimplemented: Read as '0'

bit 10-8 WDAY<2:0>: Binary Coded Decimal Value of Weekday Digit; contains a value from 0 to 6

bit 7-6 Unimplemented: Read as '0'

bit 5-4 HRTEN<1:0>: Binary Coded Decimal Value of Hour's Tens Digit; contains a value from 0 to 2

bit 3-0 HRONE<3:0>: Binary Coded Decimal Value of Hour's Ones Digit; contains a value from 0 to 9

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 27-1: PMCON: PARALLEL PORT CONTROL REGISTER (CONTINUED)

bit 2	BEP: Byte Enable Polarity bit
	 1 = Byte enable active-high (PMBE) 0 = Byte enable active-low (PMBE)
bit 1	WRSP: Write Strobe Polarity bit
	For Slave modes and Master mode 2 (PMMODE<9:8> = 00,01,10): 1 = Write strobe active-high (PMWR) 0 = Write strobe active-low (PMWR)
	For Master mode 1 (PMMODE<9:8> = 11): 1 = Enable strobe active-high (PMENB) 0 = Enable strobe active-low (PMENB)
bit 0	RDSP: Read Strobe Polarity bit
	For Slave modes and Master mode 2 (PMMODE<9:8> = 00,01,10): 1 = Read strobe active-high (PMRD) 0 = Read strobe active-low (PMRD) For Master mode 1 (PMMODE<9:8> = 11): 1 = Read/write strobe active-high (PMRD/PMWR) 0 = Read/write strobe active-low (PMRD/PMWR)

- Note 1: 28-pin devices do not have PMA<10:2>.
 - 2: These bits have no effect when their corresponding pins are used as address lines.

31.2 AC Characteristics and Timing Parameters

This section defines dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 AC characteristics and timing parameters.

TABLE 31-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

	Standard Operating Conditions: 3.0V to 3.6V
AC CHARACTERISTICS	Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial -40^{\circ}C < TA $\le +125^{\circ}C$ for Extended
	Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



TABLE 31-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions
DO50	Cosco	OSC2/SOSCO pin	_	—	15	pF	In XT and HS modes when external clock is used to drive OSC1
DO56	Сю	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	Св	SCLx, SDAx	—	_	400	pF	In I ² C™ mode

			$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$						
Param No.	Symbol	Characteristic	Min	Min Typ ⁽¹⁾ Max Units Co					
		Cloc	k Parame	eters					
AD50	TAD	ADC Clock Period	76	—	_	ns	_		
AD51	tRC	ADC Internal RC Oscillator Period		250	—	ns	—		
	Conversion Rate								
AD55	tCONV	Conversion Time		12 TAD	_	—	_		
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	_		
AD57	TSAMP	IP Sample Time		—	_	—	—		
		Timin	g Param	eters					
AD60	tPCS	Conversion Start from Sample Trigger ⁽¹⁾	2 Tad	_	3 Tad		Auto-Convert Trigger not selected		
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ⁽¹⁾	2 Tad	_	3 Tad		_		
AD62	tcss	Conversion Completion to Sample Start (ASAM = 1) ⁽¹⁾		0.5 TAD			_		
AD63	tdpu	Time to Stabilize Analog Stage from ADC Off to ADC On ⁽¹⁾			20	μs	_		

TABLE 31-47: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: The tDPU is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (AD1CON1<ADON>='1'). During this time, the ADC result is indeterminate.

TABLE 31-48: AUDIO DAC MODULE SPECIFICATIONS	TABLE 31-48:	AUDIO DAC MODULE SPECIFICATIONS
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AC/DC	CHARACT	ERISTICS	$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$				
Param No.	Symbol	Characteristic	Min	Тур	Мах	Units	Conditions
		Clo	ock Para	ameters			
DA01	VOD+	Positive Output Differential Voltage	1	1.15	2	V	Vod+ = VDACH - VDACL See Note 1,2
DA02	Vod-	Negative Output Differential Voltage	-2	-1.15	-1	V	Vod- = VDACL - VDACH See Note 1,2
DA03	Vres	Resolution	_	16		bits	—
DA04	Gerr	Gain Error		3.1		%	—
DA08	FDAC	Clock frequency	—	—	25.6	MHz	—
DA09	FSAMP	Sample Rate	0	_	100	kHz	—
DA10	FINPUT	Input data frequency	0		45	kHz	Sampling frequency = 100 kHz
DA11	ΤΙΝΙΤ	Initialization period	1024	_	_	Clks	Time before first sample
DA12	SNR	Signal-to-Noise Ratio	_	61		dB	Sampling frequency = 96 kHz

Note 1: Measured VDACH and VDACL output with respect to VSS, with 15 μA load and FORM bit (DACxCON<8>) = 0.
2: This parameter is tested at -40°C ≤ TA ≤+85°C only.

АС СНА	ARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Indus $-40^{\circ}C \le TA \le +125^{\circ}C$ for External				o 3.6V °C for Industrial °C for Extended
Param No.	Characteristic	Min	Тур	Мах	Units	Conditions
PM1	PMALL/PMALH Pulse Width	—	0.5 TCY	_	ns	—
PM2	Address Out Valid to PMALL/PMALH Invalid (address setup time)	—	0.75 TCY	—	ns	—
PM3	PMALL/PMALH Invalid to Address Out Invalid (address hold time)	—	0.25 TCY	_	ns	—
PM5	PMRD Pulse Width	—	0.5 TCY	_	ns	—
PM6	PMRD or PMENB Active to Data In Valid (data setup time)	150	—	_	ns	—
PM7	PMRD or PMENB Inactive to Data In Invalid (data hold time)	—	—	5	ns	—

TABLE 31-54: PARALLEL MASTER PORT READ TIMING REQUIREMENTS

FIGURE 31-32: PARALLEL MASTER PORT WRITE TIMING DIAGRAM



dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 AND dsPIC33FJ128MCX02/X04

IPC18 (Interrupt Priority Control 18) 127, 128
IPC2 (Interrupt Priority Control 2)
IPC3 (Interrupt Priority Control 3)
IPC4 (Interrupt Priority Control 4)
IPC5 (Interrupt Priority Control 5)
IPC6 (Interrupt Priority Control 6)
IPC7 (Interrupt Priority Control 7)
IPC8 (Interrupt Priority Control 8)
IPC9 (Interrupt Priority Control 9) 121
NVMCON (Elash Memory Control) 75
NVMKEY (Nonvolatile Memory Key) 76
OCxCON (Output Compare x Control) 212
OSCCON (Oscillator Control) 147
OSCTUN (ERC Oscillator Tuning) 151
P1DC3 (PWM Duty Cycle 3) 226
PLLEBD (PLL Eeedback Divisor) 150
PMD1 (Perinheral Module Disable Control Register 1)
PMD2 (Perinheral Module Disable Control Register 2)
160
PMD3 (Perinheral Module Disable Control Register 3)
161
PWMxCON1 (PWM Control 1) 220
$\frac{220}{PWMxCON2} (PWM Control 2) $
PyDC1 (PWM Duty Cycle 1) 226
P_{XDC1} (FWM Duty Cycle 2) 226
PXDC2 (FWW Duly Cycle 2)
PXDTCON1 (Dead-Time Control 2) 222
PXDTCON2 (Dead-Time Control)
PXFLTACON (Fault A Control)
PXOVDCON (Overlide Control)
PXSECMP (Special Event Compare)
PXTCON (PWM Time Base Control). 217, 300, 301, 302
PXTMR (PVVM Timer Count value)
PXTPER (PWM Time Base Period)
QEICON (QEI Control)
RCON (Reset Control)
SPIXCON1 (SPIX Control 1)236
SPIXCONZ (SPIX Control 2)
SPIXSTAT (SPIX Status and Control)
SR (CPU Status)
11CON (Timer1 Control)
ICxCON (Input Capture x Control)
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TyCON (Type C Time Base Control)
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UXSTA (UARTX Status and Control)
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10-bit ADC Conversion (CHPS<1:0> = 01 SIMSAM	1 = 0
ASAM = 1 SSRC<2.0> = 111	,
SAMC < 4.0 > = 0.0001	405
$10-\text{bit}$ ADC Conversion (CHPS<1:0> = 01_SIMSAN	1 = 0
$ASAM = 1 SSDC_2 \cdot 05 = 111 SAMC_2 \cdot 1$	n = 0, n > -
A0001	405
12 bit ADC Conversion (ACAM = 0. CCDC < 2:0) = -	405
12-bit ADC Conversion (ASAM = $0, SSRC<2.0$ =	000)
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UART Module

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Temperature and Voltage Specifications

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

Microchip Trader Architecture — Flash Memory Fa Program Memory Product Group Pin Count — Tape and Reel Fla Temperature Ran Package — Pattern —	nark — mily — v Size (Kl ag (if app ge —	dsPIC 33 FJ 32 MC3 02 T E / SP - XXX	Examples: a) dsPIC33FJ32MC302-E/SP: Motor Control dsPIC33, 32 KB program memory, 28-pin, Extended temperature, SPDIP package.
Architecture:	33 =	16-bit Digital Signal Controller	
Flash Memory Family:	FJ :	Flash program memory, 3.3V	
Product Group:	MC2 = MC3 = MC8 =	Motor Control family Motor Control family Motor Control family	
Pin Count:	02 = 04 =	28-pin 44-pin	
Temperature Range:	I = E = H =	-40° C to+85° C (Industrial) -40° C to+125° C (Extended) -40° C to+150° C (High)	
Package:	SP = SO = ML = MM = PT =	Skinny Plastic Dual In-Line - 300 mil body (SPDIP) Plastic Small Outline - Wide - 300 mil body (SOIC) Plastic Quad, No Lead Package - 8x8 mm body (QFN) Plastic Quad, No Lead Package - 6x6x0.9 body (QFN-S) Plastic Thin Quad Flatpack - 10x10x1 mm body (TQFP)	